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TITLE: A METHOD AND SYSTEM FOR UNIVERSAL PACKAGING IN CONJUNCTION WITH A BACK-END INTEGRATED CIRCUIT MANUFACTURING PROCESS

INVENTOR(S): Bo Soon Chang and Vani Verma

USSN: 10/086,050 ATTORNEY DOCKET #: CYPR-PM01032



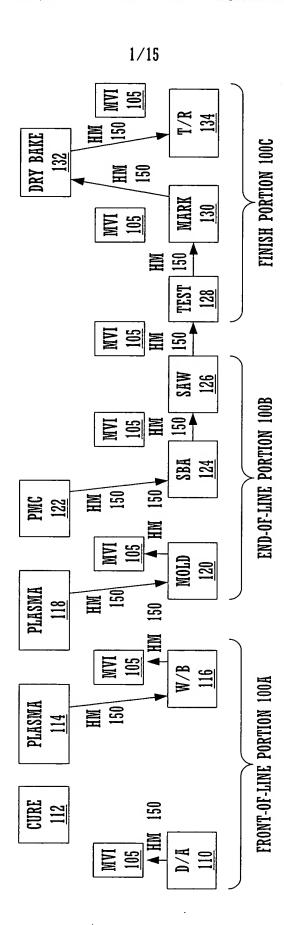


FIGURE 1

INTEGRATED CIRCUIT MANUFACTURING PROCESS

INVENTOR(S): Bo Soon Chang and Vani Verma

USSN: 10/086,050 ATTORNEY DOCKET #: CYPR-PM01032



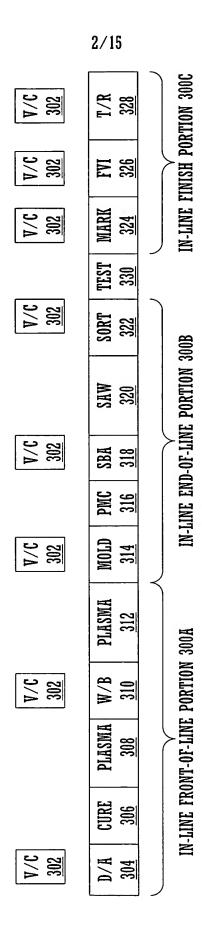


FIGURE 2

INVENTOR(S): Bo Soon Chang and Vani Verma

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IN-LINE FRONT-OF-LINE PORTION PLASMA

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SORT 322 SAW 320 IN-LINE END-OF-LINE PORTION PINC 316 MOLD 314

INTEGRATED CIRCUIT MANUFACTURING PROCESS

INVENTOR(S): Bo Soon Chang and Vani Verma 10/086,050 ATTORNEY DOCKET #: CYPR-PM01032 USSN: 10/086,050

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IN-LINE FINISH PORTION FVI 326 MARIK 324

INTEGRATED CIRCUIT MANUFACTURING PROCESS INVENTOR(S): Bo Soon Chang and Vani Verma

USSN: 10/086,050 ATTORNEY DOCKET #: CYPR-PM01032



									
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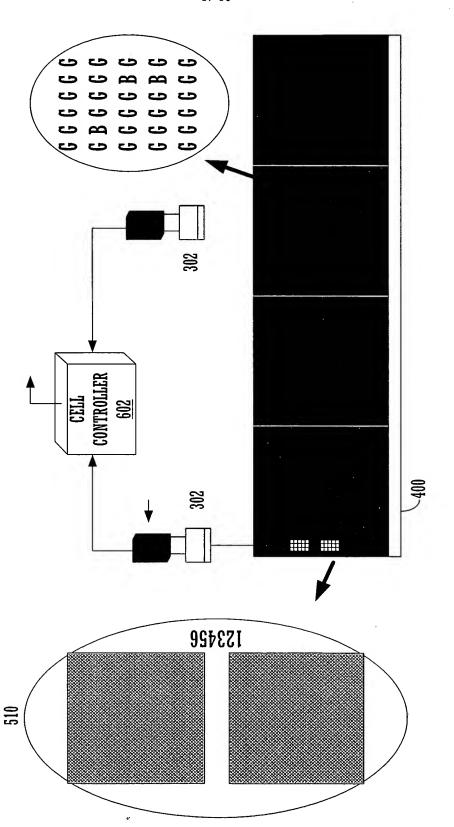


FIGURE 5

INTEGRATED CIRCUIT MANUFACTURING PROCESS INVENTOR(S): Bo Soon Chang and Vani Verma

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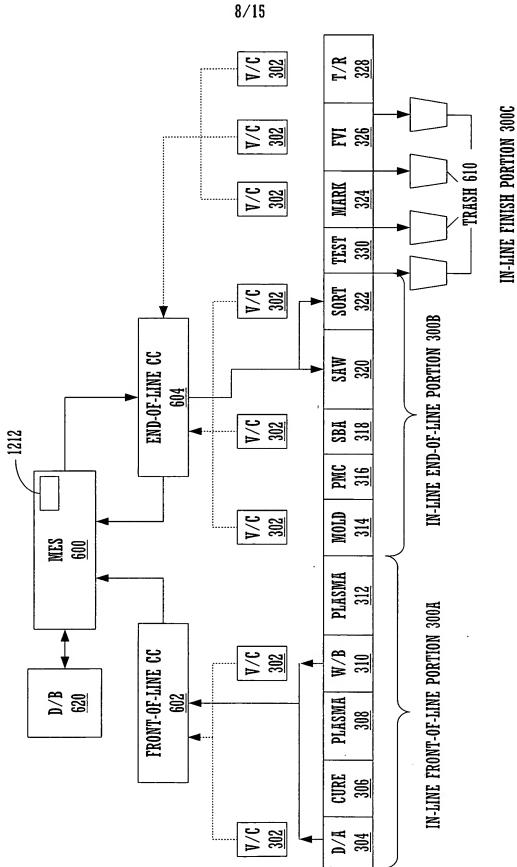


FIGURE 6

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FIGURE 7

INVENTOR(S): Bo Soon Chang and Vani Verma

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START

PROCESSING A DIE-STRIP THROUGH A FRONT-OF-LINE ASSEMBLY PORTION WHICH COMPRISES A PLURALITY OF SUB-STATIONS OPERATING ON AN IN-LINE BASIS.

802

AUTOMATICALLY PROVIDING THE DIE-STRIP TO AN END-OF-LINE ASSEMBLY PORTION.

804

PROCESSING THE DIE-STRIP BY THE END-OF-LINE ASSEMBLY PORTION WHICH COMPRISES A PLURALITY OF SUB-STATIONS OPERATING ON AN IN-LINE BASIS.

806

AUTOMATICALLY PROVIDING THE DIE-STRIP TO A TEST ASSEMBLY PORTION.

808

TESTING THE DIE-STRIP USING THE TEST ASSEMBLY PORTION.

810

AUTOMATICALLY PROVIDING THE DIE-STRIP TO A FINISH ASSEMBLY PORTION. 812

PROCESSING THE DIE-STRIP BY THE FINISH ASSEMBLY PORTION WHICH COMPRISES A PLURALITY OF SUB-STATIONS OPERATING ON AN IN-LINE BASIS.

814

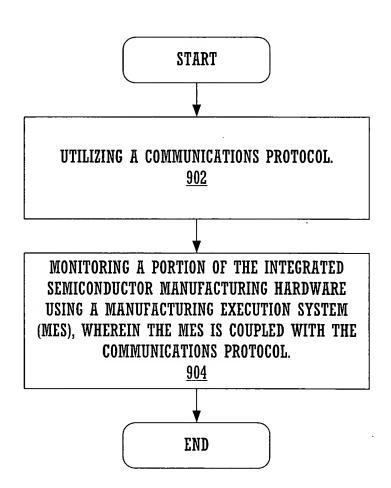
END

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INVENTOR(S): Bo Soon Chang and Vani Verma
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1000

START

IMPLEMENTING A TRACKING PROCESS FOR THE DIE-STRIP WHICH IDENTIFIES INDIVIDUAL DIE-STRIPS AND THEIR RESPECTIVE LOCATIONS AS THEY TRAVERSE THROUGH THE IN-LINE ASSEMBLY LINE.

<u>1002</u>

ACCESSING AN ELECTRONIC DIE-STRIP MAP DATABASE THAT PROVIDES PARAMETER STORAGE FOR EACH INDIVIDUAL SEMICONDUCTOR COMPONENT WITHIN EACH DIE-STRIP.

1004

UTILIZING THE TRACKING PROCESS TO UPDATE THE ELECTRONIC DIE-STRIP MAP DATABASE AT EACH SUBSTATION THAT COLLECTS PARAMETER INFORMATION.

1006

CATEGORIZING THE DIE ON THE DIE-STRIP BASED ON INFORMATION MAINTAINED BY THE ELECTRONIC DIE-STRIP MAP DATABASE AND SPECIFICALLY REJECTING BAD DIE AND USING PARAMETER INFORMATION TO SORT DIE.

1008

END

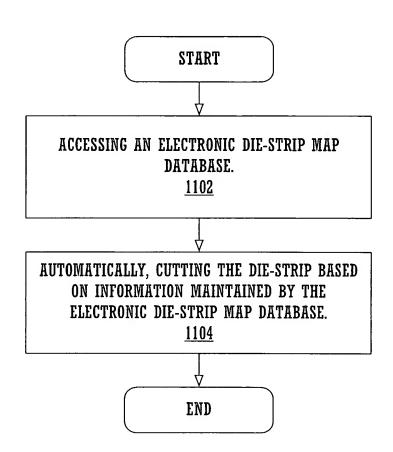
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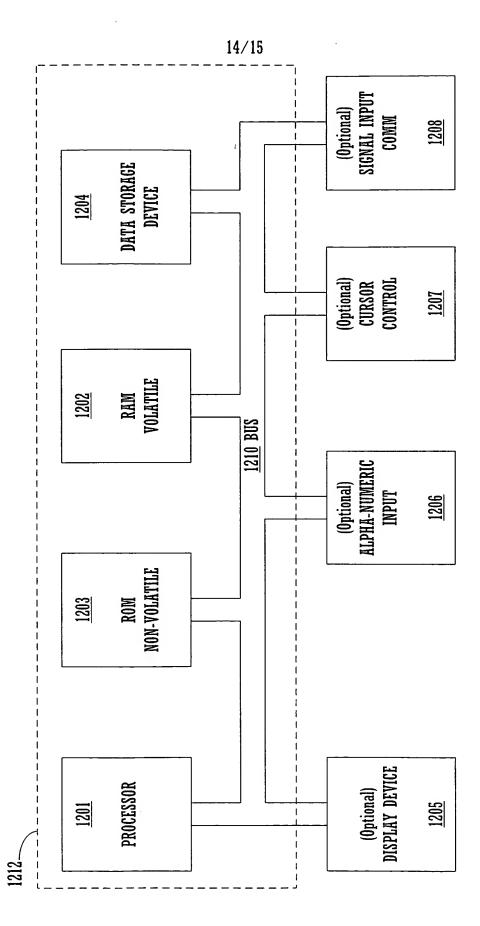


FIGURE 12

INTEGRATED CIRCUIT MANUFACTURING PROCESS

INVENTOR(S): Bo Soon Chang and Vani Verma
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